

REVISION				
ZONE	REV	DESCRIPTION	DATE	APPROVED
	A	INITIAL RELEASE	12/11/00	A. BOLD
	A1	CHANGES AS PER ECR-093054	10FEB20	

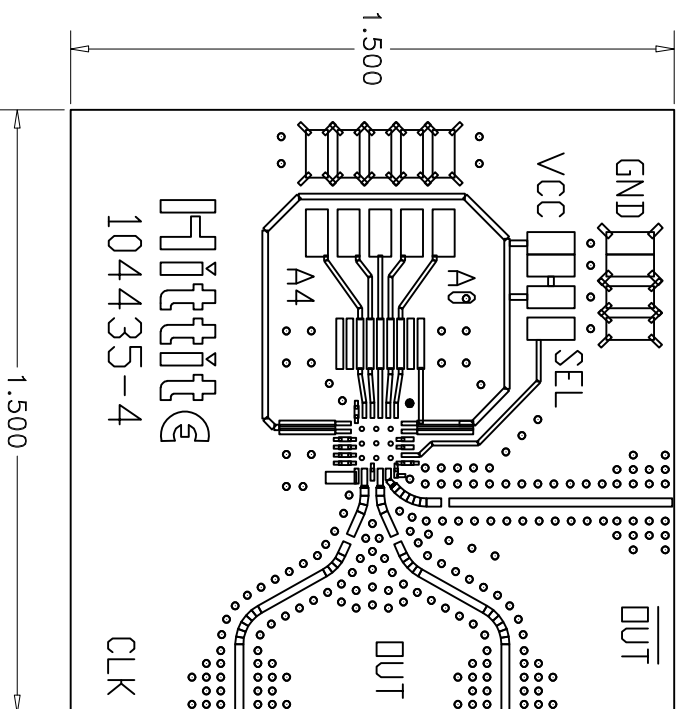
MET-1	1/2 OZ COPPER
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0.010"±0.001 ROGERS 4350
SEE NOTE # 1

MET-2 1/2 OZ COPPER

NOTES: UNLESS OTHERWISE SPECIFIED

1. MATERIAL "MULTILAYER" OVERALL STACKUP AS SHOWN. TYPE ROGERS 4350, HALF OUNCE COPPER BOTH SIDES.
2. FINISH: ENIG (ELECTROLESS NICKEL/MMEMSION GOLD)
PER IPC-4552 LATEST REVISION.
3. PLATED THRU HOLES: .001" MINIMUM WALL THICKNESS.
4. HOLE SIZES AND POSITIONS PER ARTWORK AND/OR DRILL FILE.
5. ALL HOLES TO BE LOCATED WITHIN $\pm .003$ " OF THE CENTER OF THE PAD OR OTHER TRUE POSITION.
6. FRONT TO BACK REGISTRATION $\pm .003$ " MAX
7. BOARD WARPAGE: .010" PER LINEAR INCH MAX
8. SILKSCREEN TOPSIDE ONLY WITH WHITE EPOXY INK
9. TOLERANCE ON PCB ROUTE IS $\pm .005$ "
10. PLATING THICKNESS: .0018" $\pm .0005$ FOR MET-1 AND MET-2
11. APPLY LPI SOLDERMASK TOPSIDE ONLY. COLOR: GREEN
*** SOLDERMASK TO BE APPLIED AS DESIGNED. ANY ADJUSTMENTS TO SOLDERMASK MUST FIRST BE APPROVED BY HITITTE MICROWAVE.
12. REMOVE METAL BURRS FROM EDGE OF PCB AFTER PANEL SEPERATION.
13. METAL ARTWORK IS 1:1. VENDOR TO ADJUST FOR ETCH FACTOR.
14. BACKSIDE IS SOLID GROUND PLANE
15. THRU VIAS FILLED WITH NON-CONDUCTIVE EPOXY AND PLATED OVER.




CRITICAL LINE WIDTH = $.020 \pm .001$ ADJUST PROCESS TO ACHIEVE WIDTH

PROPRIETARY TO HITITE MICROWAVE CORPORATION

TABLE 1 : HOLE DIAMETERS				
LETTER DESIGN.	DIAMETER	QTY	TYPE	NOTES
NONE	0.018	182	PTH	SEE NOTE 15
NONE	0.012	9	PTH	SEE NOTE 15

UNLESS OTHERWISE SPECIFIED:		DRAWN
DIMENSIONS ARE IN INCHES (MM)		A. BOLD 12/7/00
DRAWING PRACTICES PER MIL-STD-100		CHECKED
TOLERANCES:		ENG. APPD.
.XX	+/- .01	
.XXX	+/- .005	HMC APPD.
ANGLES	+/- .5 DEG	RELEASED

		
HITITE MICROWAVE CORPORATION 12 Elizabeth Drive Chelmsford, MA 01824		
TITLE EVALUATION PCB HMC394LP4		
SIZE	CODE ID NO.	DRAWING NO.
A	1CN88	104435
SCALE 2 TO 1	WT	SHEET 1 OF 1